JOC306XD5 Series

Rev.A.1.0

DESCRIPTION:

The products are 5-pin thyristor opto-couplers. The device combines an AIGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-crossing photo triac in a plastic DIP5 package with different lead forming options. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 265 V_{AC} peripherals.

MAIN FEATURES

High isolation 5000 VRMS
DC input with zero-crossing photo triac output
Operating temperature range -55 to 110
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Off-state Output Terminal Voltage	V_{OFF}	600	V
		I_{TP}	2	A
	On-state RMS Current	$I_{T(RMS)}$	100	mA
	Peak Repetitive Surge Current (P_W=10 ms)	I_{TSM}	1.2	A
	Output Power Dissipation	P_O	250	mW
Total Power Dissipation		P_{tot}	325	mW

Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-55~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage (T_j=25 ; non-repetitive,off-state)	V_{pp}	1	kV

NOTE1 100μs pulse, 100Hz frequency

NOTE2

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

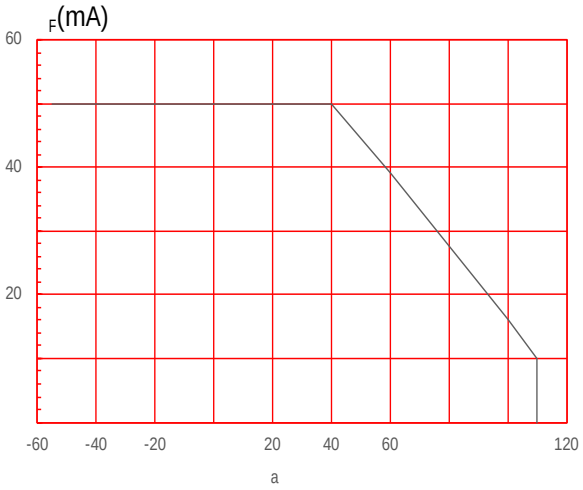
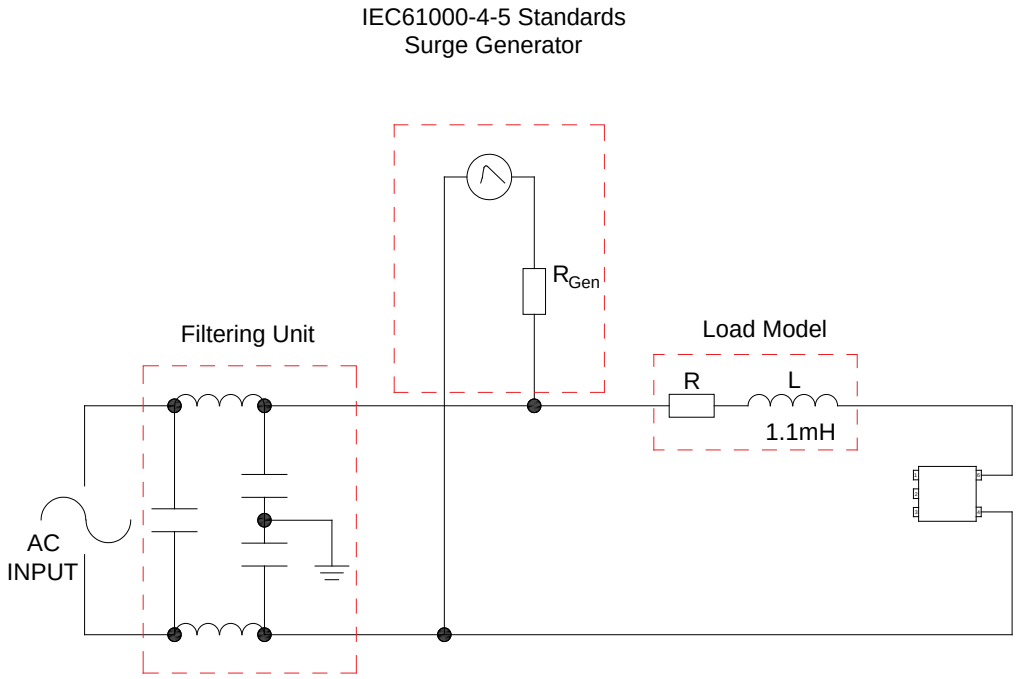


FIG.2: On-state Terminal Current vs. Ambient Temperature

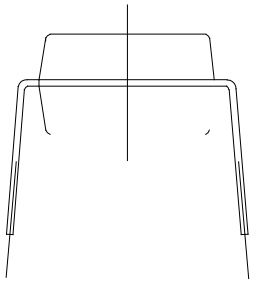
FIG.7: Normalized On-

FIG.16: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



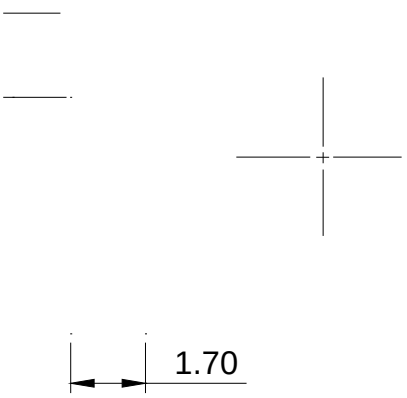
Package Dimension (Unit: mm)

Standard DIP Type:



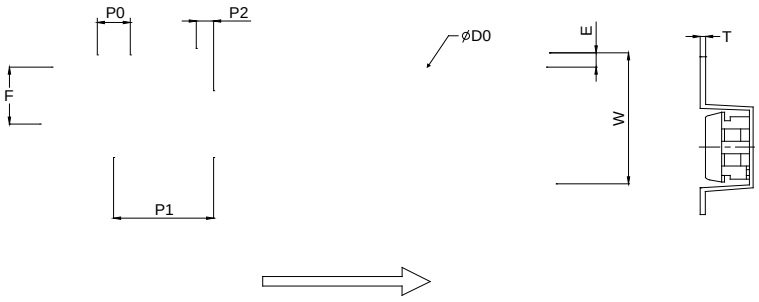
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD



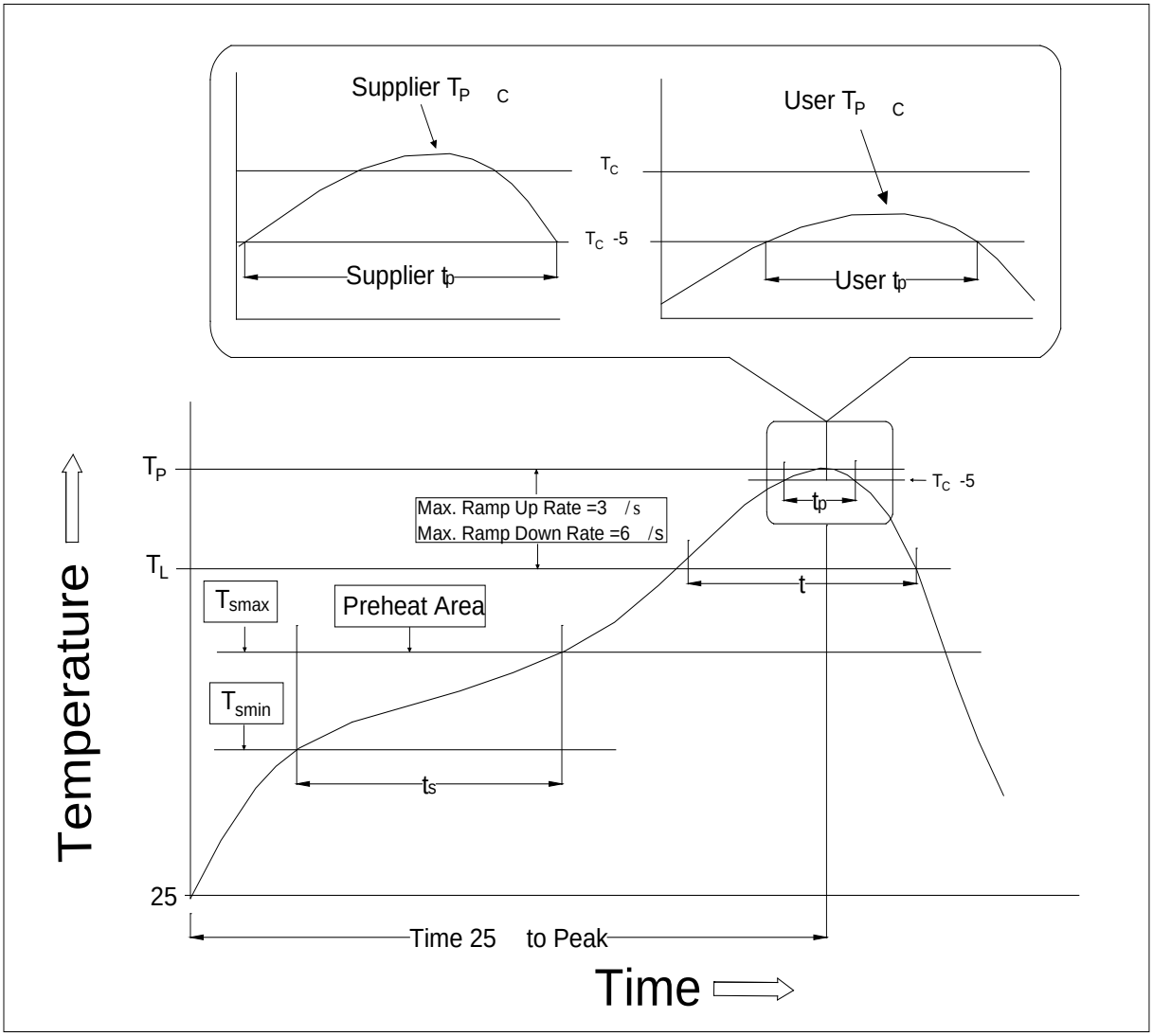
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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